DOCUMENT CHANGE REQUEST

DCR number 148	Changes required for: N/A	Originator: MOUTON Alain
Date: 2005/03/28	Date sent: 2005/03/28	Organisation:
Status: IMPLEMENTED		

Title:	Generic Specification for Integrated Circuits Monolithic		
Number:	9000	Issue:	3

Other documents affected:

Page:

Page 19 Para. 8.16 SolderabilityPage 26 Chart F3 Screening Tests

Paragraph:

Page 19 Para. 8.16 SolderabilityPage 26 Chart F3 Screening Tests

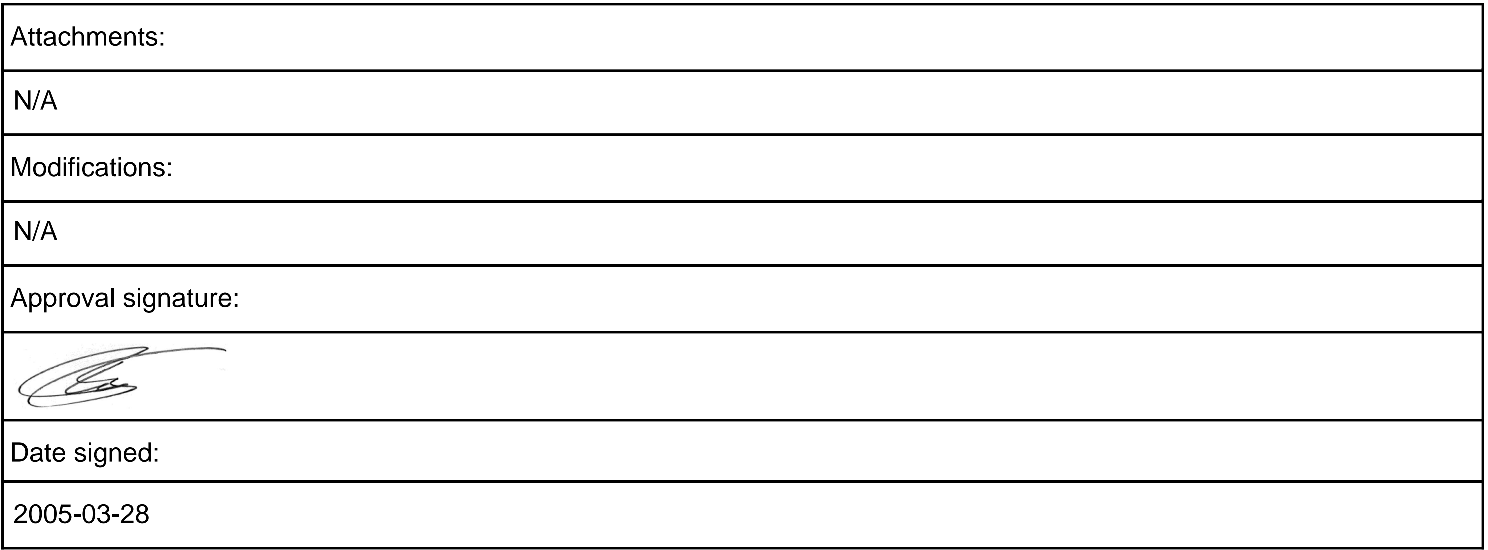
Original wording:

Proposed wording:

1) Use of OA flux to be re-instated for components with gold plated leads. i.e. 4th subpara changed to read:"For components with gold plated lead finish activated fluxes (RMA, RA and OA) may be used but shall be immediately cleaned off after dipping using an acceptable solvent."2) chart F3. Add inspection step "Hot Solder Dip (if applicable)" with new "Note 5" after Para. 8.9.2 High and low Temperatures Electrical Measurements and before Room Temperature Electrical Measurements.Notes are renumbered to match the sequence in which they appear in Chart F3.Note 5 shall read:5. For components with hot solder dip final lead finish the hot solder dip processing shall be eprformed at any time prior to Room Temperature Electrical Measurements during Screening Tests. The requriements for hot solder dip are specified in ESCC Basic Specification No. 23500.

Justification:

1) OA flux may be required to be used in some cases.2) These tests are proposed to be added to prevent any risk of loss of hermeticity following the hot solder dip operation. such concerns were already met on Semicoa products (ESA alert EA-2003-EEE-07-A and GIDEP advisory IB7-P-03-01) and possibly met on other SMD parts from other manufacturers.Please note that the MIL system is currently updating the MIL-PRF-19500 specification (draft N) to consider this concern.This DCR was rewritten by the Secretariat to match the mark-up of 9000 dated 3rd June and PSWG 18.



Attachments:
N/A
Modifications:
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